# Comparison of performances of candidate ITK layouts

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# OUTLINE

### Introduction CERN - LHC

#### ATLAS - Inner Tracker

Future Inner Tracker (ITk) - Upgrade motivations Future Inner Tracker (ITk) - Upgrade characteristics

#### Simulation

2D plot - location of material in RZ plane 1D plot - weight of the detector ( $X_0$  plot) Physics performances

### Conclusion

# CERN - LHC

- Near Geneva (Switzerland), laboratory on Nuclear Physics and Particle Physics
- Built the largest and the most powerful (p/p) circular collider





- LHC has a circumference of 27km
- Located 100m below the ground
- Collides protons and also Pb

# LHC - high luminosity program

LHC nominal : 14 TeV,  $1 \times 10^{34} cm^{-2} s^{-1}$ 



- Higgs discovered with Run 1 data (7-8 TeV)
- LHC has reached the unprecedented center-of-mass energy of 13TeV in 2015

- High Luminosity program aims to increase by a factor 10 the integrated luminosity (up to 300 fb<sup>-1</sup> per year)
- Increases DATA  $\rightarrow$  reduce statistical errors
  - make precise measurement / search on rare channel

# ATLAS

 $\partial \theta$ 

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Pseudorapidity  $\eta \equiv -\ln | tan(\frac{\theta}{2}) |$ 

# 3D-view of the current Inner Tracker



3 sub-detectors : Pixel detector (granularity =  $50 \times 400 \ [\mu m]$ ) Semiconductor Tracker (SCT - granularity =  $80 \ [\mu m]$  strip) and Transition Radiation Tracker (TRT - granularity = 40 diameter 1440 length [mm])

# Longitudinal view of the Inner Detector



• Angular acceptance :  $\eta = 2.7$ 

# Required performances for Inner Tracker (current and future)

To design an ITk, physicists need to be focused on :

- the granularity, ITk measures momentum and direction of all tracks
- the spatial resolution in order to detect the beginning of particle jets (lifetimes)
- weight to ensure that tracking detector will not cause to many multiple scattering, lose of particles due to interactions, i.e., minimize secondary hits
- angular acceptance in order to observe jets in the forward region
- radiation hardness, efficiency

# Inner Tracker (ITk) - Upgrade motivations

Upgrade : in a tougher environment, we want to keep, at least, the same reconstruction performances of tracks (efficiency,  $p_T$ , primary and secondary vertices)

- High Luminosity  $\rightarrow$  + pile-up (from 20 to 200 inelastic pp collisions), + occupancy (more hits)
  - TRT will be abandoned (cell size/granularity too high)
  - Pixel and SCT : OK (Silicon  $\rightarrow$  radiation tolerance)
- Current ITk designed for an instantaneous luminosity of  $\mathcal{L} = 1 \times 10^{34} \ cm^{-2}s^{-1}$  and at the HL-LHC  $\mathcal{L} = 7.5 \times 10^{34} \ cm^{-2}s^{-1}$  is expected
- Search in the forward region
  - increase angular acceptance



- That leads to an increased radiation environment, a more complicated tracking reconstruction
- $\implies$  the Inner Tracker has to be replaced and improved (upgrade)

# Inner Tracker (ITk) - Upgrade characteristics

- ITk will be designed only with Silicon because of its radiation tolerance
- Covers a larger region (expl : VBF process  $H \rightarrow 4I$ ) from  $\mid \eta \mid \leq 2.7$  (current ITk) to  $\mid \eta \mid \leq 3.2$  or 4
- Innovative upgrade  $\rightarrow$  Alpine Pixel Detector
  - Challenge : Tracking performance and cooling





Geometry aspect of the Alpine pixel sensor



• Simulation of particle's trajectory at 20° ( $\eta=1.7$ )

- Idea of inclined sensor : cross sensor orthogonally (important at large  $\eta$ )  $\rightarrow$  tracking performances
- Particle can hit more sensors  $\rightarrow$  + precision BUT more material are hit !? sensor's thickness !
- $\bullet$  Less sensors  $\to$  less electrical cables & reduction of sensor area  $\to$  reduction of passive material
- Reduce amount of material of sensors (cost)



# 4 candidate layouts for the upgrade ITk



# 4 candidates of ITk for the upgrade layout



# Simulation - 2D plot

# 2D plot

- First tools to simulate and reconstruct ITk in order to compare layouts (began at the start of 2016)
- Goal : compare of performances  $\rightarrow$  I worked on first geometry versions  $\rightarrow$  debugging period
- I participated to the development of 2D plot to show where/what the matter is
- In order to see the detector's geometry OR if matter is missing (for debugging purpose too)
- Simulation with GEANT4, use of geantinos (particle does not interact with matter, no mass, no charge)
- Geantinos are sent in every direction through detector then simulation records the crossing material (type, position) to reconstructed material distribution

# 4 layouts - RZ Silicon (active part)

ExtBrl32 v15 M Silicon





# 4 layouts - RZ CarbonFiber





IExtBrl4 v5 M Services



Missing parts !



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# 1D-plot ( $X_0$ plot)

 $X_0$  plot (radiation length)  $\Rightarrow$  the amount of material sensitive to electromagnetic interaction

$$-\left\langle \frac{dE}{dx}\right\rangle = \frac{1}{X_0}E \Rightarrow E(x) = E_0 e^{-x/X_0} \tag{1}$$

- Use of the attenuation formula
- 1  $X_0 \Leftrightarrow$  length over an  $e^-$  looses 1/e of its energy;
- 1  $X_0 \Leftrightarrow \frac{7}{9}$  of the mean free path for  $e^-/e^+$  production by a  $\gamma$
- Represent the material 'cost' for particle to pass

# 1D plot - Total X0 against $\eta$ per detector volume



η

# 1D plot - Total X0 against $\eta$ per material

InclBrl4\_v15



### How are we going to compare

Total X0



# Simulation - Physics performances

# Physics performances

- ITk measures momentum and direction of all tracks
  - $\bullet\,$  with a good spatial (temporal) resolution  $\rightarrow\,$  impact parameters
  - limit material (X<sub>0</sub> plot) to reduce multiple scattering and lose of particle's energy
- For the simulation, I used sample of single  $\mu$ -lepton and  $e^-$  at  $p_T = 10 100 \ GeV$ , whose paths trough the detector was simulated
- We have a good efficiency to say that simulation is good enough to give clues on physics performances





# Physics performances - $q/p_T$ against $\eta$



# Spatial resolution - Impact parameters



- In (x,y) plan, d<sub>0</sub> ⇔ closest point : particle's curvature / collision point
  - to measure decay point for  $\tau$ -lepton, B-hadrons, ...
- $z_0 \Leftrightarrow$  value of z where  $d_0$  is evaluated
  - to separate primary vertices of pile-up events from hard scattering event

# Spatial resolution - $d_0$ against $\eta$



# Spatial resolution - $z_0$ against $\eta$



# Spatial resolution - change of the size of pixel's sensor



# Conclusion

- Single particle currently show better tracking performances for inclined layout
- Tracking improvements are still expected
- To be evaluated with more complex events (expl : *tt*)
- Electron performances to be evaluated on combination with calorimeters
- At the end of 2016, choice of the layout
- At the end of 2017, Technical Design Report will define the baseline layout

# Thanks for your attention ! Questions ?

# **BACK-UP**

- Internship at Laboratory of Annecy-le-Vieux of Particle Physics (LAPP)
- LAPP works on big experiences : AMS, HESS, CTA, Virgo, Stereo, SuperNEMO, WA105, R&D on future collider, LHCb and ATLAS
- ATLAS group at LAPP works on data analyses  $(H \rightarrow \gamma \gamma, \gamma \gamma \text{ at 750 GeV}, WZ \rightarrow 3I, Z' \rightarrow 2I)$ , on LAr calorimeter and on tracking system

# HL-LHC - Physics motivation



• High luminosity  $\rightarrow$  more data

- Improves precision on already observed decay mode  $(H \rightarrow ZZ, \gamma\gamma, WW, \tau\tau, bb)$
- Observation on rare Higgs decays mode and rare Higgs production mode
- Searches on rare channel :
  - WH/ZH,  $H \rightarrow \gamma\gamma$
  - $t\bar{t}H, H \rightarrow \gamma\gamma$
  - $H \rightarrow \mu \mu$

# RZ Silicon InclBrl4





### RZ Support structure vs Sensor - InclBrl4

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For rel delaging only:

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Not be used as in inclusion of the that detector inyrate:

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InclBrl4\_v5\_M\_CarbonFiber

InclBrl4\_v5\_M\_Silicon



# LoI



# VBF process



